

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	5697	(257/776,777,778,779,780,781,784,786).CCLS.	USPAT	2006/02/20 14:34
2	IS&R	L2	3632	(257/776,777,778,779,780,781,784,786).CCLS.	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/02/20 14:35
3	BRS	L3	1854	((((wire adj (bond bonding)) (wire-(bond bonding))) and ((flip adj chip) (flip-chip))) and ((257/776,777,778,779,780,781,784,786).CCLS.)	USPAT	2006/02/20 14:38
4	BRS	L4	814	((((wire adj (bond bonding)) (wire-(bond bonding))) and ((flip adj chip) (flip-chip))) and ((257/776,777,778,779,780,781,784,786).CCLS.)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	2006/02/20 14:38
5	BRS	L5	268	((438/107,108,109,110,117,123,612,614).CCLS.) and (mcm or mcms)	USPAT	2006/02/20 14:56
6	BRS	L6	502	((((257/776,777,778,779,780,781,784,786).CCLS.) or ((257/685,686,700).CCLS.) or ((257/666,673,674,676).CCLS.)) and mcm	USPAT	2006/02/20 14:57
7	BRS	L7	1	((((wire wiring) near2 chip) and (flipchip flip-chip flip adj chip) and (mold molding) and (extension) and (recession recess)).clm.	US-PGPUB	2006/02/20 14:59